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### Understanding [Embedded - FPGAs \(Field Programmable Gate Array\)](#)

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

### Applications of Embedded - FPGAs

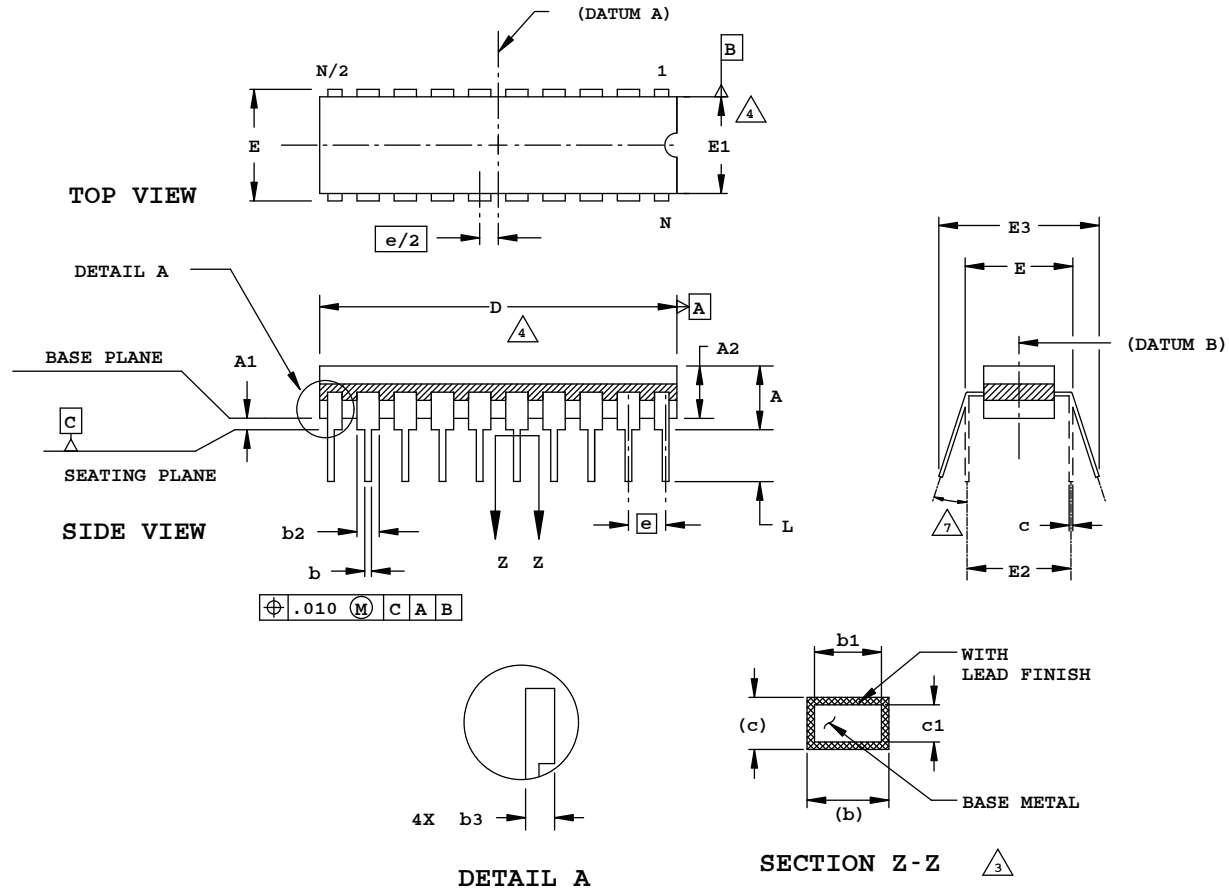
The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications.

#### Details

Product Status	Obsolete
Number of LABs/CLBs	-
Number of Logic Elements/Cells	3100
Total RAM Bits	56320
Number of I/O	67
Number of Gates	-
Voltage - Supply	1.14V ~ 1.26V
Mounting Type	Surface Mount
Operating Temperature	0°C ~ 85°C (TJ)
Package / Case	100-LQFP
Supplier Device Package	100-TQFP (14x14)
Purchase URL	<a href="https://www.e-xfl.com/product-detail/lattice-semiconductor/lfec3e-4t100c">https://www.e-xfl.com/product-detail/lattice-semiconductor/lfec3e-4t100c</a>

## 20-Pin (300-Mil) CERDIP Package

Dimensions in Inches



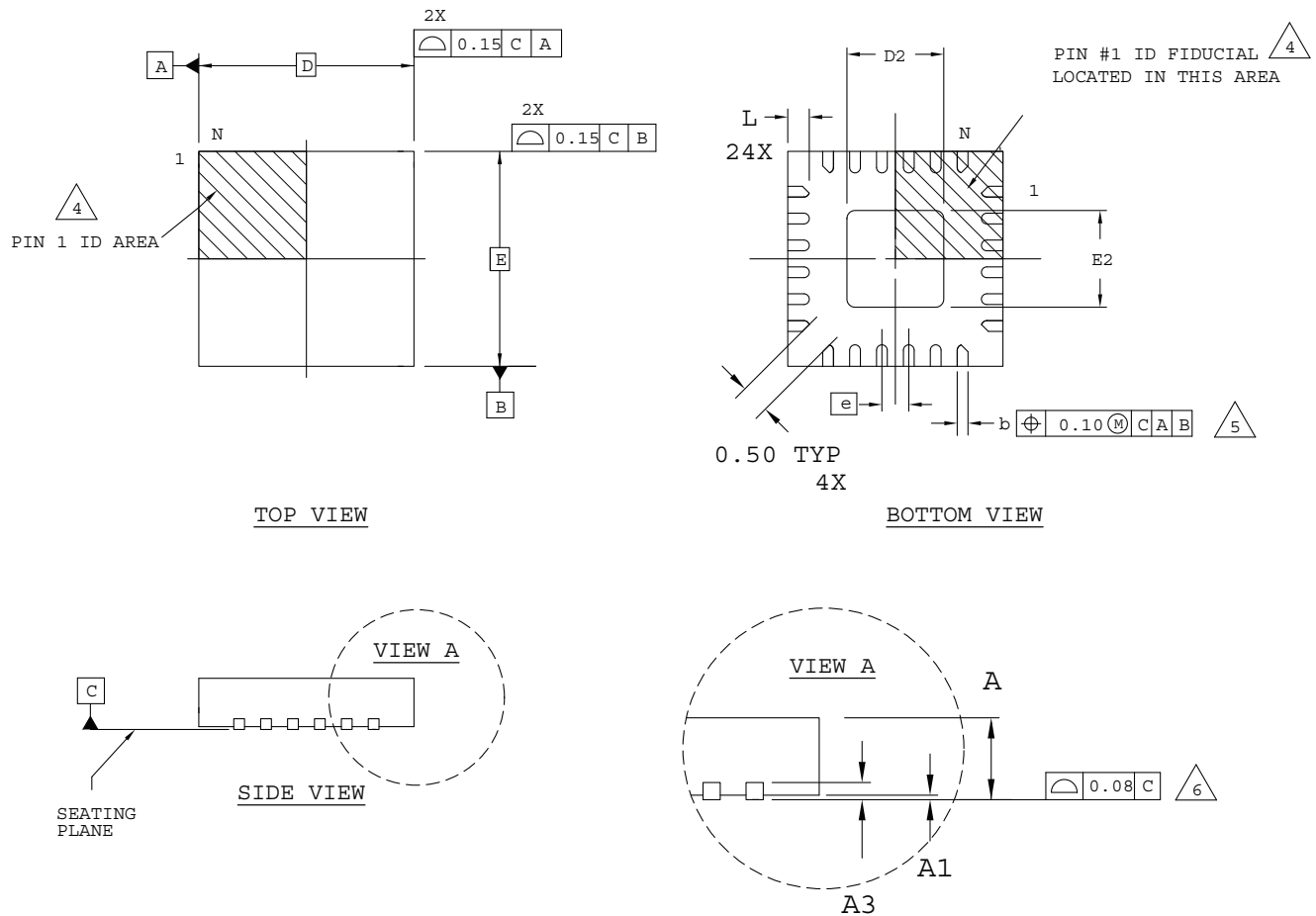
### NOTES:

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M.
2. ALL DIMENSIONS ARE IN INCHES.
3. MEASUREMENTS TO BE TAKEN AT A MINIMUM OF .060 INCHES FROM THE LEAD TIP.
4. DIMENSIONS D AND E1 INCLUDE ALLOWANCE FOR GLASS OVERRUN AND MENISCUS, AND LID TO BASE MISMATCH.
5. DIMENSIONS A, A1 AND L ARE MEASURED WITH THE PACKAGE SEATED IN JEDEC SEATING PLANE GAUGE GS-003.
6. E3 IS TO BE MEASURED AT THE LEAD TIPS.
7. ALLOWED LEAD TIP POSITION RANGE.

SYMBOL	INCHES		
	MIN.	NOM.	MAX.
A	-	-	.200
A1	.015	-	-
A2	.140	-	.175
b	.015	-	.023
b1	.015	.018	.021
b2	.045	-	.065
b3	.023	-	.045
c	.008	-	.014
c1	.008	.010	.012
D	.942	.950	.970
E	.308	-	.325
E1	.280	.288	.296
E2	.300 REF		
E3	.325	-	.410
e	.100 BSC		
L	.125	-	.200
N	20		

## 24-Pin QFNS Package

Dimensions in Millimeters



NOTES: UNLESS OTHERWISE SPECIFIED

1. DIMENSIONS AND TOLERANCES PER ANSI Y14.5M.
2. ALL DIMENSIONS ARE IN MILLIMETERS.
3. DRAWING CONFORMS TO JEDEC MO-220, VARIATION VGGD-9.

△ 4 EXACT SHAPE AND SIZE OF THIS FEATURE IS OPTIONAL.

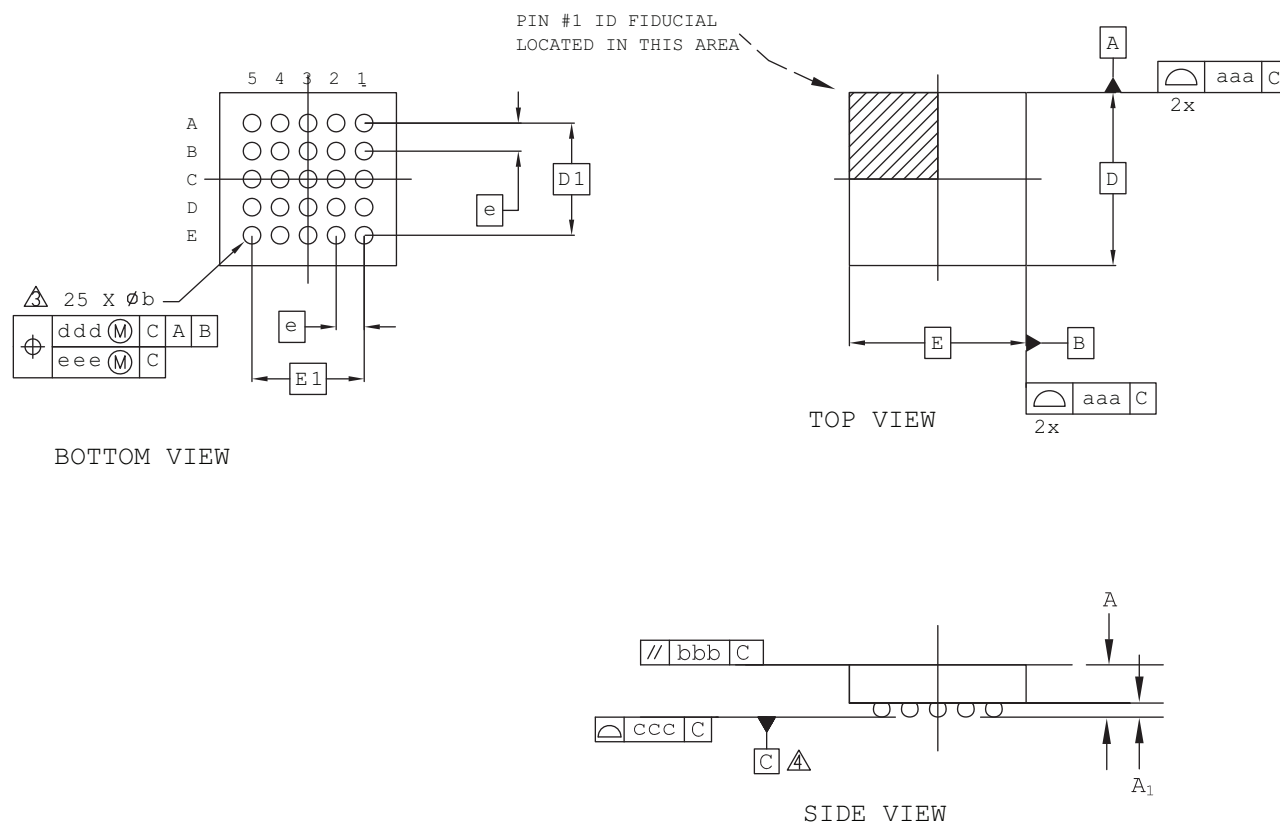
△ 5 DIMENSION b APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.15 AND 0.30 mm FROM TERMINAL TIP.

△ 6 APPLIES TO EXPOSED PORTION OF TERMINALS.

SYMBOL	MIN.	NOM.	MAX.
A	0.80	0.90	1.00
A1	0.00	0.02	0.05
A3	0.2 REF		
D	4.0 BSC		
D2	1.05	-	2.45
E	4.0 BSC		
E2	1.05	-	2.45
b	0.18	0.25	0.30
e	0.50 BSC		
L	0.45	0.50	0.55

## 25-Ball WLCS Package (0.40 mm Pitch)

Dimensions in Millimeters



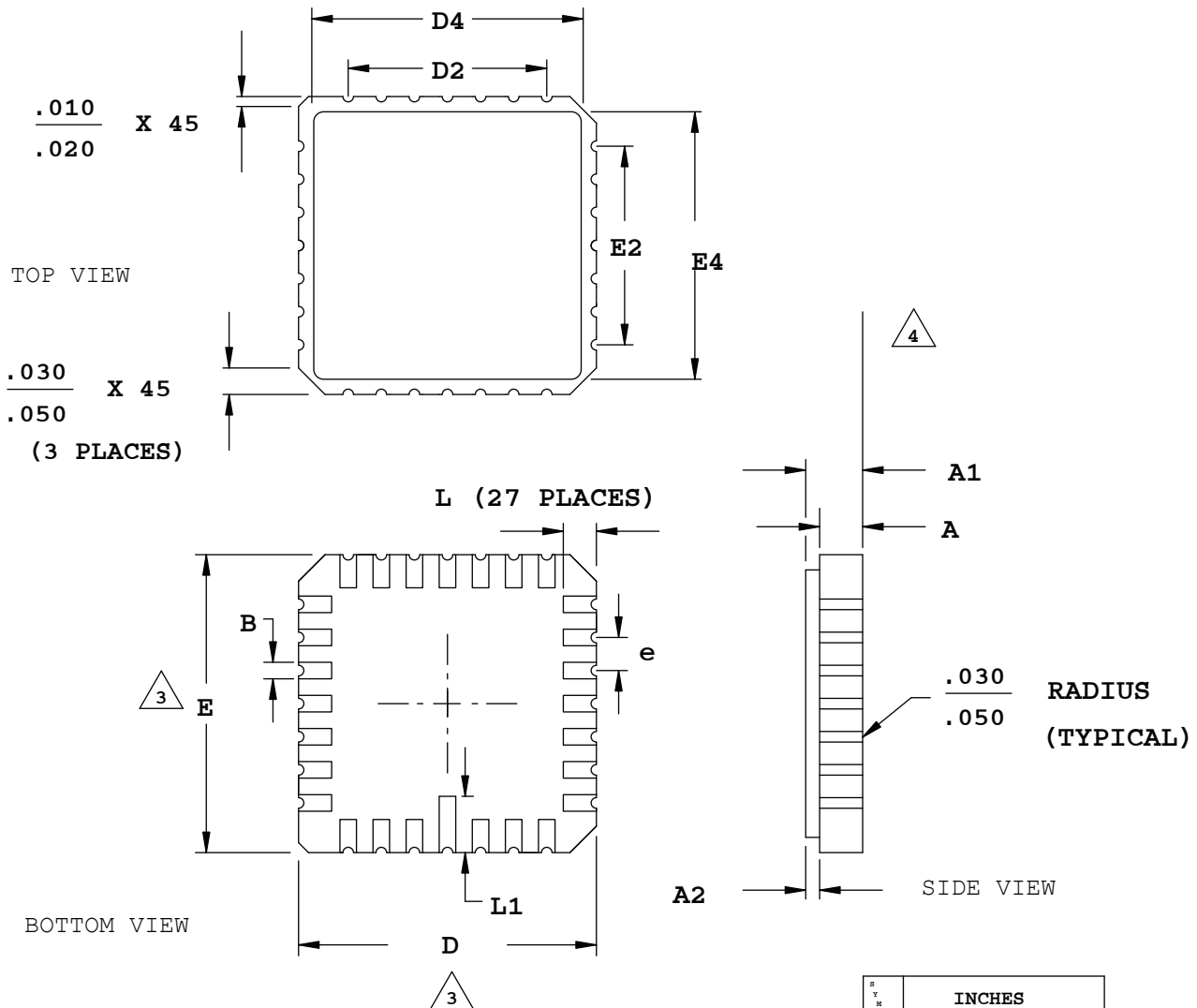
### Notes:

- 1 ALL DIMENSIONS AND TOLERANCE PER ASME Y 14.5M - 1994.
- 2 ALL DIMENSIONS ARE IN MILLIMETERS.
- 3 DIMENSION "b" IS MEASURED AT THE MAXIMUM BUMP DIAMETER PARALLEL TO PRIMARY DATUM C.
- 4 PRIMARY DATUM C AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BUMPS.

REF.	Min.	Nom.	Max.
A	0.535	0.575	0.615
A1	0.170	0.200	0.230
b	0.220	0.250	0.280
D	2.492 BSC		
E	2.546 BSC		
D1	1.60 BSC		
E1	1.60 BSC		
e	0.40 BSC		
aaa	0.025		
bbb	0.060		
ccc	0.015		
ddd	0.150		
eee	0.050		

## 28-Pin LCC Package

Dimensions in Inches



### NOTES:

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5.
2. ALL DIMENSIONS ARE IN INCHES.

3. DIMENSIONS D AND E MAY HAVE MATERIAL PROTRUSION OF .010 INCHES MAXIMUM ABOVE THE DIMENSION SHOWN NOT TO EXCEED .005 INCHES MAXIMUM PER SIDE.

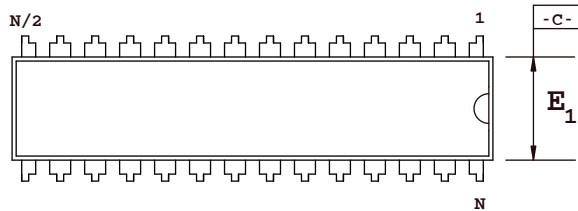
4. FLATNESS TOLERANCE IS .004 INCHES PER INCH.

SYMBOL	INCHES		
	MIN.		MAX.
A	.054		.074
A1	.064		.089
A2	.007		.015
B	.022		.028
D	.440		.460
D2		.300	
D4	.370		.403
E	.440		.460
E2		.300	
E4	.370		.403
e		.050 BSC	
L	.042		.058
L1	.075		.095

## 28-Pin Plastic DIP Package

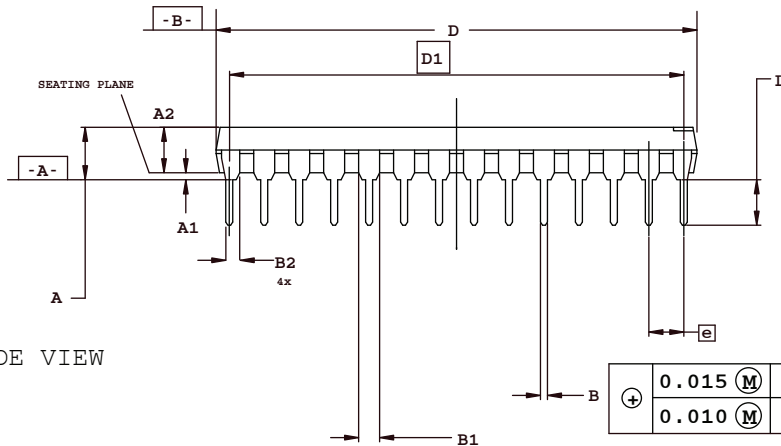
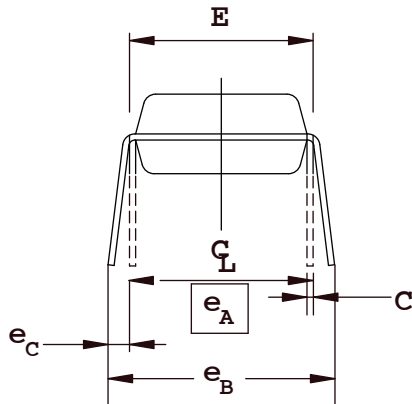
Dimensions in Inches

TOP VIEW



NOTE:

- 1 CONTROLLING DIMENSION: INCHES
- 2 DIMENSIONING AND TOLERANCING  
PER ANSI Y14.5M-1982
- 3 ALL END LEADS IN THIS FAMILY ARE 1/2 LEADS
- 4 DIMENSION A, A1, AND L ARE MEASURED WITH THE  
PACKAGE SEATED IN JEDEC SEATING PLANE GAUGE GS-3
- 5 D AND E1 DIMENSIONS DO NOT INCLUDE MOLD  
FLASH OR PROTRUSION. MOLD FLASH AND  
PROTRUSION SHALL NOT EXCEED 0.010
- 6 E AND eA MEASURED WITH THE LEADS  
CONSTRAINED TO BE PERPENDICULAR TO PLANE A
- 7 eB AND eC ARE MEASURED AT THE LEAD TIPS  
WITH THE LEADS UNCONSTRAINED. eC MUST BE  
ZERO OR GREATER
- 8 N IS THE NUMBER OF TERMINAL POSITIONS
- 9 B1 AND B2 MAXIMUM DIMENSIONS DO NOT INCLUDE  
DAMBAR PROTRUSIONS. DAMBAR PROTRUSIONS  
SHALL NOT EXCEED 0.010



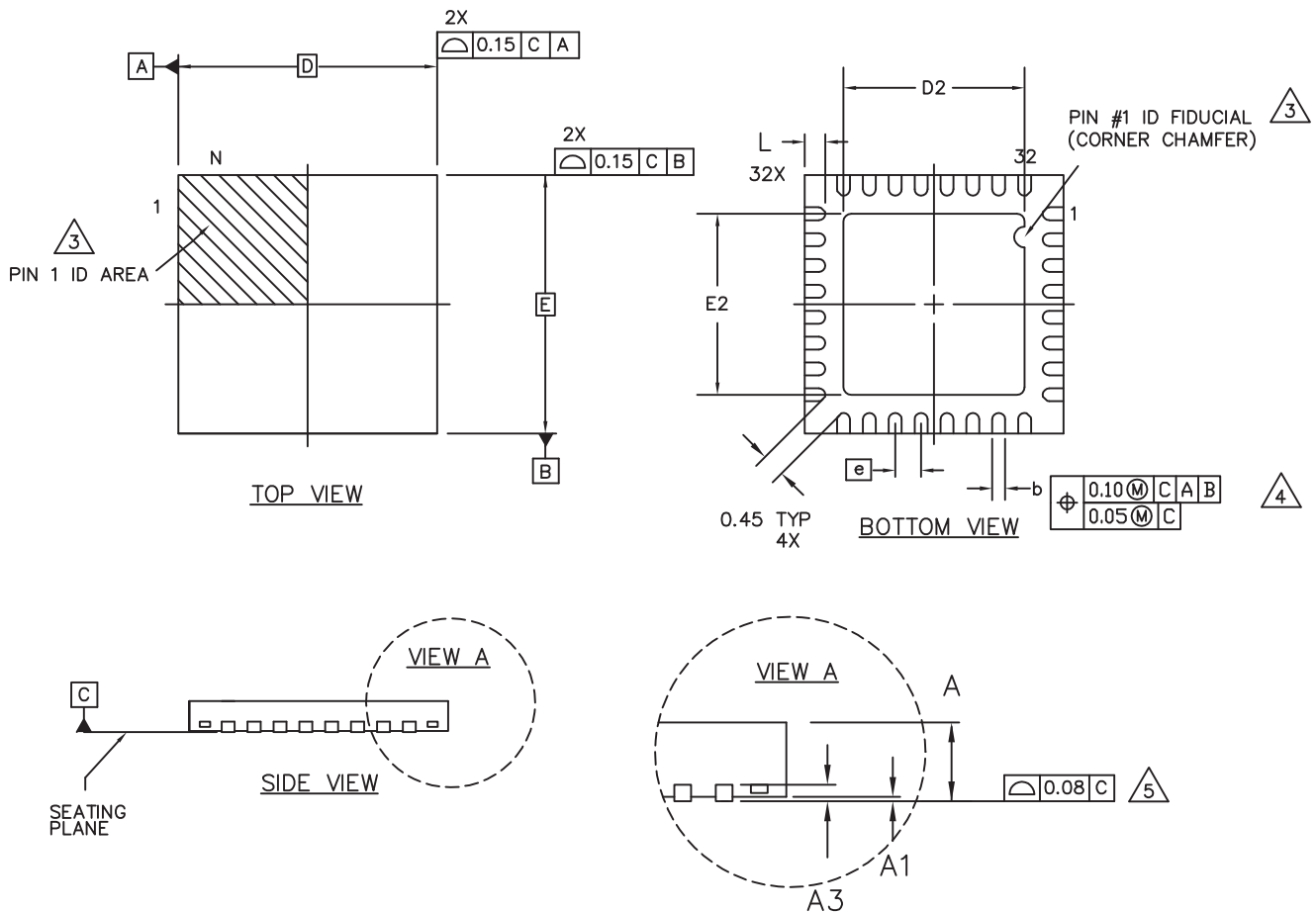
SIDE VIEW

SYMBOL	INCHES		
	MIN.	NOM.	MAX.
A	-	-	.180
A1	.015	-	-
A2	.120	.135	.150
B	.014	.018	.022
B1	.045	.050	.060
B2	.030	.040	.045
C	.008	.010	.015
D	1.345	1.365	1.385
D1	1.300 BSC		
E	.300	.310	.325
E1	.275	.285	.295
e	.100 BSC		
eA	.300 BSC		
eB	-	-	.430
eC	.000	-	.060
L	.110	.130	.150
N	28		

+	0.015 (M)	A	B	C
	0.010 (M)	A		

### 32-Pin QFN Package Option 3: MachXO2 SG32C

### Dimensions in Millimeters



NOTES: UNLESS OTHERWISE SPECIFIED

1. DIMENSIONS AND TOLERANCES  
PER ANSI Y14.5M.
2. ALL DIMENSIONS ARE IN MILLIMETERS.

 EXACT SHAPE AND SIZE OF THIS  
FEATURE IS OPTIONAL.

 DIMENSION b APPLIES TO PLATED  
TERMINAL AND IS MEASURED BETWEEN  
0.15 AND 0.30 mm FROM TERMINAL TIP.

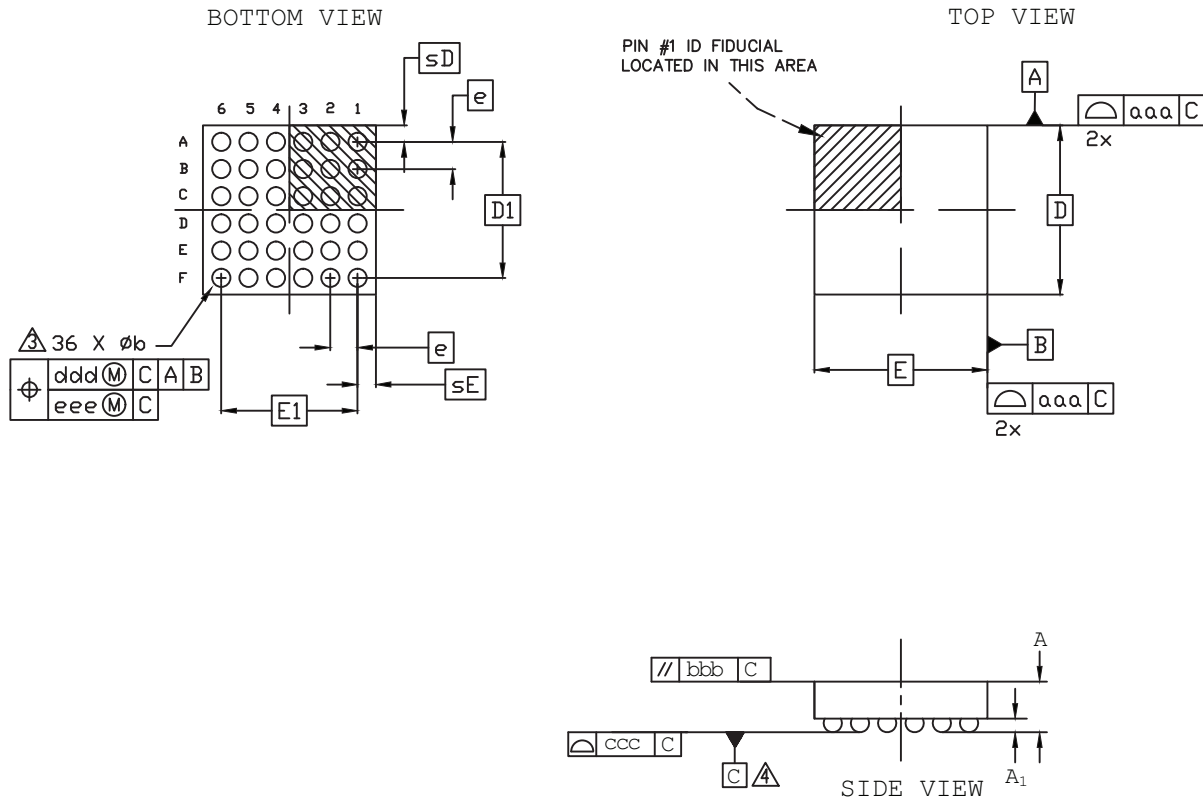
5 APPLIES TO EXPOSED PORTION OF TERMINALS.

6. JEDEC REFERENCE MO-248 AND DR-4.2

SYMBOL	MIN.	NOM.	MAX.
A	0.50	0.55	0.65
A1	0.00	0.02	0.05
A3	0.2 REF		
D	5.0 BSC		
D2	3.40	3.50	3.60
E	5.0 BSC		
E2	3.40	3.50	3.60
b	0.18	0.25	0.30
e	0.50 BSC		
L	0.35	0.40	0.45

## 36-Ball WLCS Package Option 2: MachXO3™

Dimensions in Millimeters



### NOTES:

1. ALL DIMENSIONS AND TOLERANCE PER ASME Y 14.5M - 1994.
2. ALL DIMENSIONS ARE IN MILLIMETERS.

△ DIMENSION "b" IS MEASURES AT THE MAXIMUM BUMP DIAMETER PARALLEL TO PRIMARY DATUM [C].

△ PRIMARY DATUM [C] AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BUMPS.

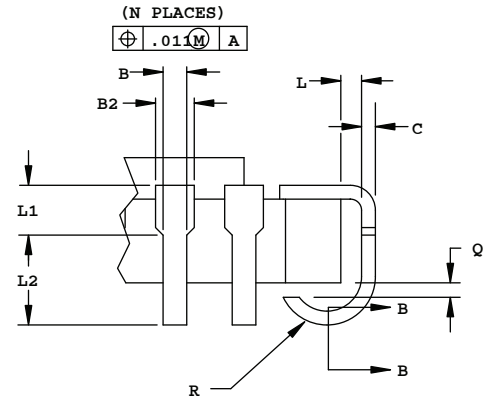
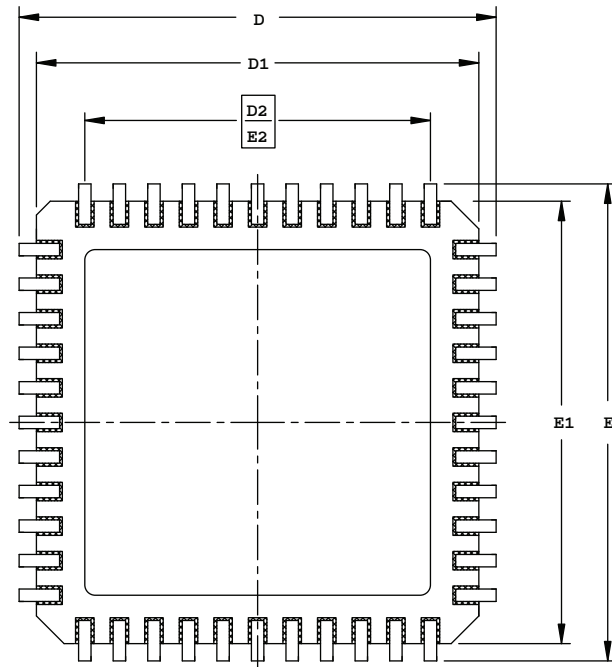
REF.	Min.	Nom.	Max.
A	0.510	0.543	0.576
A1	0.167	0.196	0.225
b	0.239	0.266	0.319
D	2.487 BSC		
E	2.541 BSC		
D1	2.00 BSC		
E1	2.00 BSC		
e	0.40 BSC		
sD	-	0.244	-
sE	-	0.271	-
aaa	0.025		
bbb	0.060		
ccc	0.030		
ddd	0.0150		
eee	0.050		



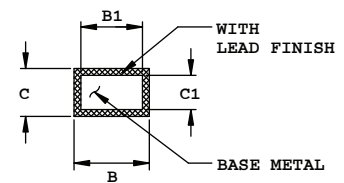
## 44-Pin JLCC Package

Dimensions in Inches

BOTTOM VIEW

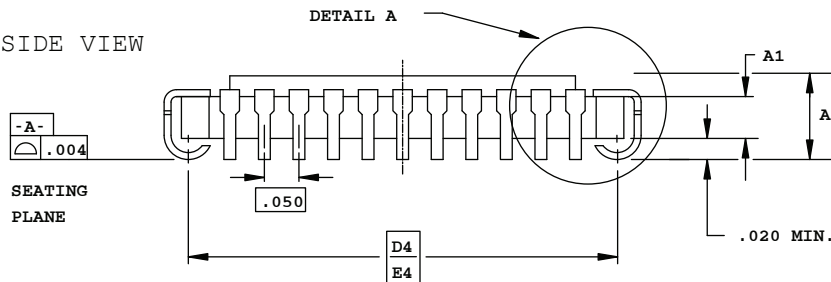


DETAIL A



SECTION B-B

SIDE VIEW



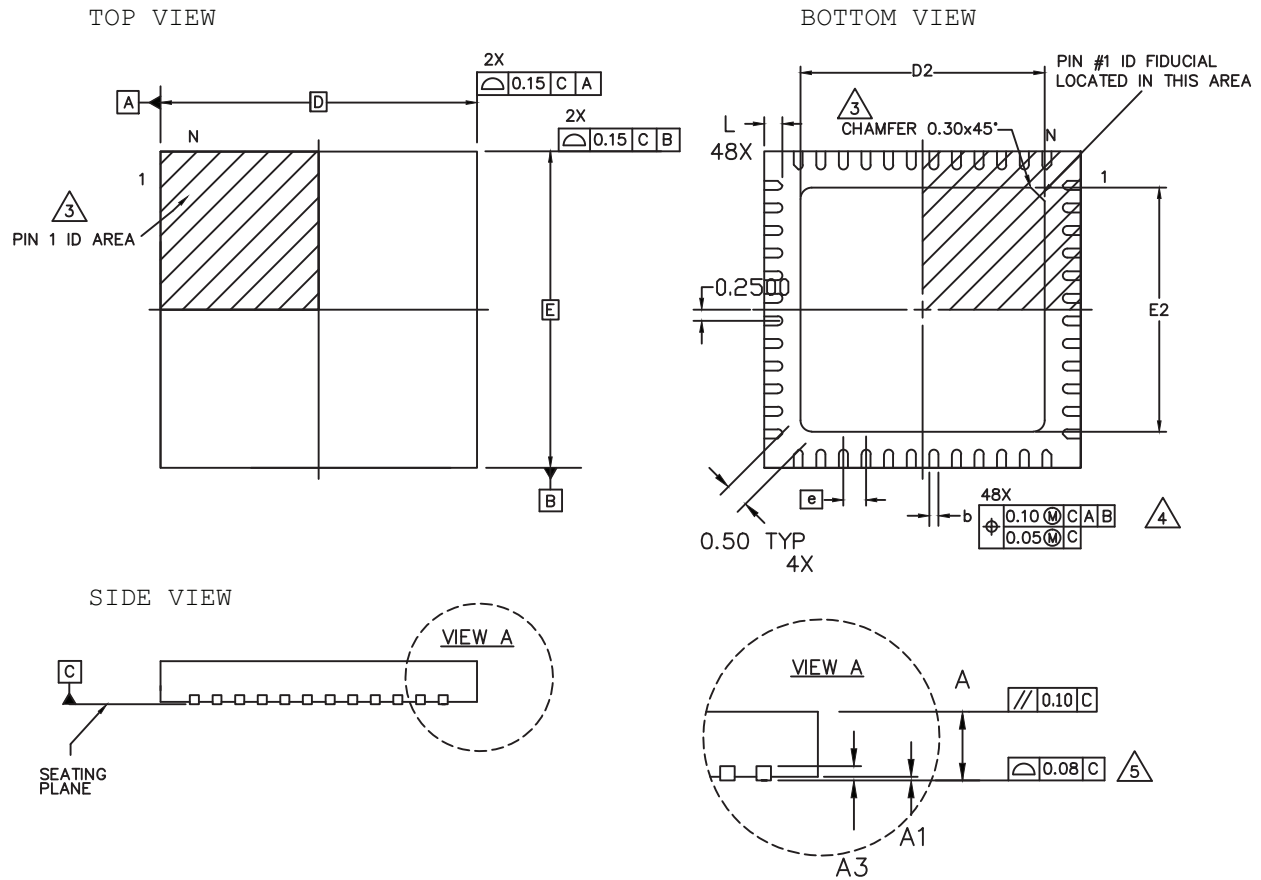
### NOTES :

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M.
2. ALL DIMENSIONS ARE IN INCHES.
3. CORNER CHAMFERS AND/OR NOTCHES ARE OPTIONAL.

SYMBOL	INCHES		
	MIN.		MAX.
A	.115	-	.190
A1	.065 REF		
B	.013	-	.023
B1	.013	-	.020
B2	.022	-	.035
C	.007	-	.013
C1	.007	-	.010
D/E	.675	.690	.700
D1/E1	.620	-	.660
D2/E2	.500 BSC		
D4/E4	.630 BSC		
L	.005	-	-
L1	.020	-	-
L2	.025	-	-
Q	.003	-	-
R	.020	-	.040
N	44		


## 48-Pin QFN Package Option 2: L-ASC10, iCE40 Ultra, iCE40 UltraPlus, MachXO2


Dimensions in Millimeters



NOTES: UNLESS OTHERWISE SPECIFIED

1. DIMENSIONS AND TOLERANCES PER ANSI Y14.5M.
2. ALL DIMENSIONS ARE IN MILLIMETERS.

 EXACT SHAPE AND SIZE OF THIS FEATURE IS OPTIONAL.

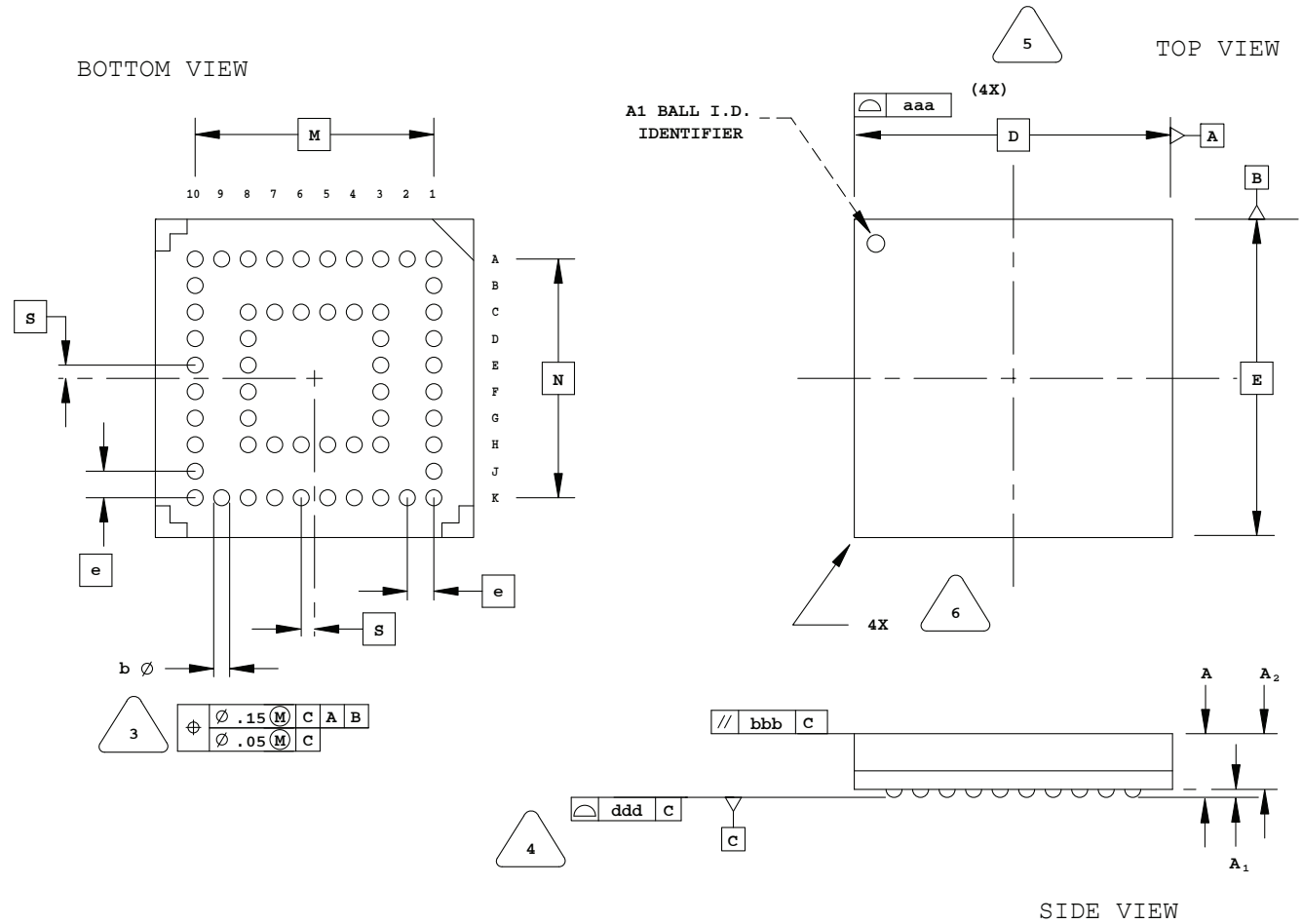
 DIMENSION b APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.15 AND 0.30 mm FROM TERMINAL TIP.

 APPLIES TO EXPOSED PORTION OF TERMINALS.

SYMBOL	MIN.	NOM.	MAX.
A	0.80	0.90	1.00
A1	0.00	0.02	0.05
A3	0.2 REF		
D	7.0 BSC		
D2	5.30	5.40	5.50
E	7.0 BSC		
E2	5.30	5.40	5.50
b	0.15	0.20	0.25
e	0.50 BSC		
L	0.35	0.40	0.45

## 56-Ball csBGA Package

Dimensions in Millimeters



NOTES: UNLESS OTHERWISE SPECIFIED

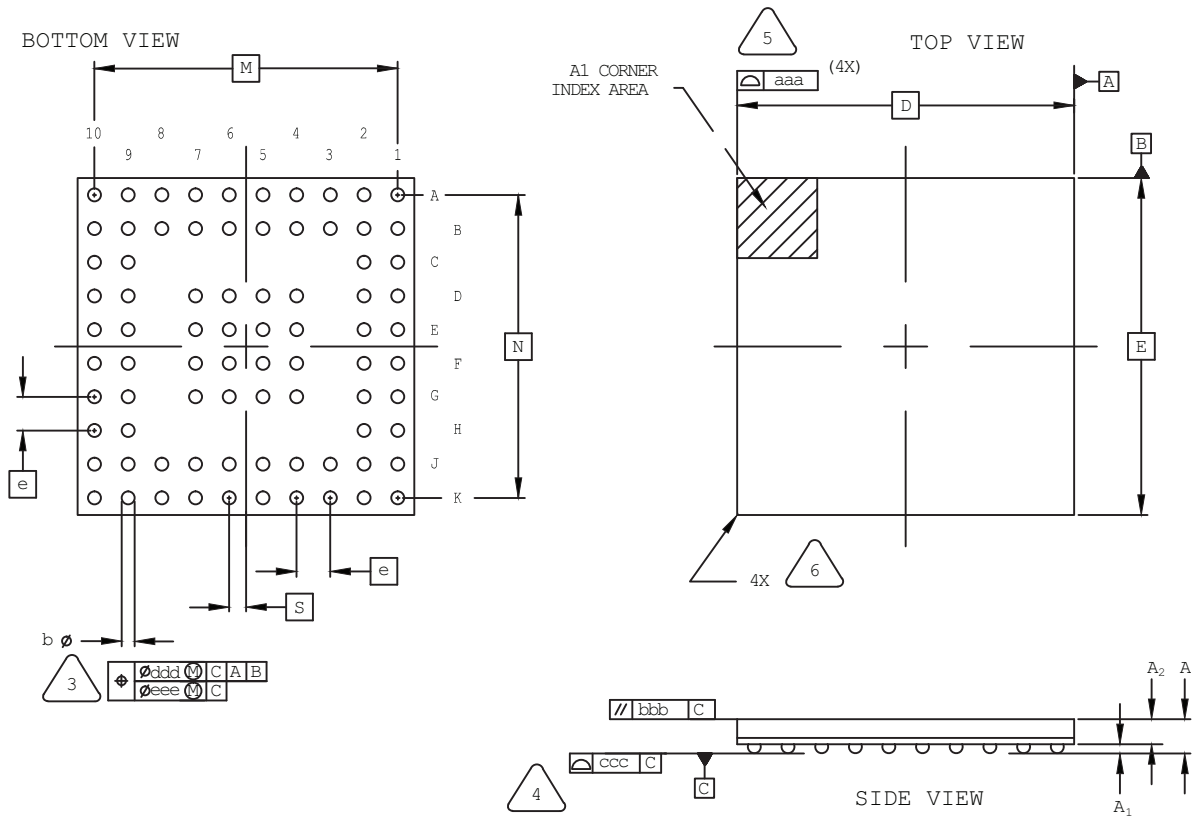
1. DIMENSIONS AND TOLERANCES PER ANSI Y14.5M.
2. ALL DIMENSIONS ARE IN MILLIMETERS.

3. DIMENSION "b" IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM [C]
4. PRIMARY DATUM [C] AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.
5. BILATERAL TOLERANCE ZONE IS APPLIED TO EACH SIDE OF THE PACKAGE BODY.
6. EXACT SHAPE AND SIZE OF THIS FEATURE IS OPTIONAL.

SYMBOL	MIN.	NOM.	MAX.
A	1.10	1.23	1.35
A1	0.15	-	-
A2	-	-	1.10
D/E	6.00 BSC		
M/N	4.50 BSC		
S	0.25 BSC		
b	0.25	0.30	0.35
e	0.50 BSC		
aaa	-	-	0.10
bbb	-	-	0.10
ddd	-	-	0.08

## 80-Ball ctfBGA Package

Dimensions in Millimeters



NOTES: UNLESS OTHERWISE SPECIFIED

1. DIMENSIONS AND TOLERANCES PER ANSI Y14.5M.
2. ALL DIMENSIONS ARE IN MILLIMETERS.



DIMENSION "b" IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM [C].



PRIMARY DATUM [C] AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.



BILATERAL TOLERANCE ZONE IS APPLIED TO EACH SIDE OF THE PACKAGE BODY.

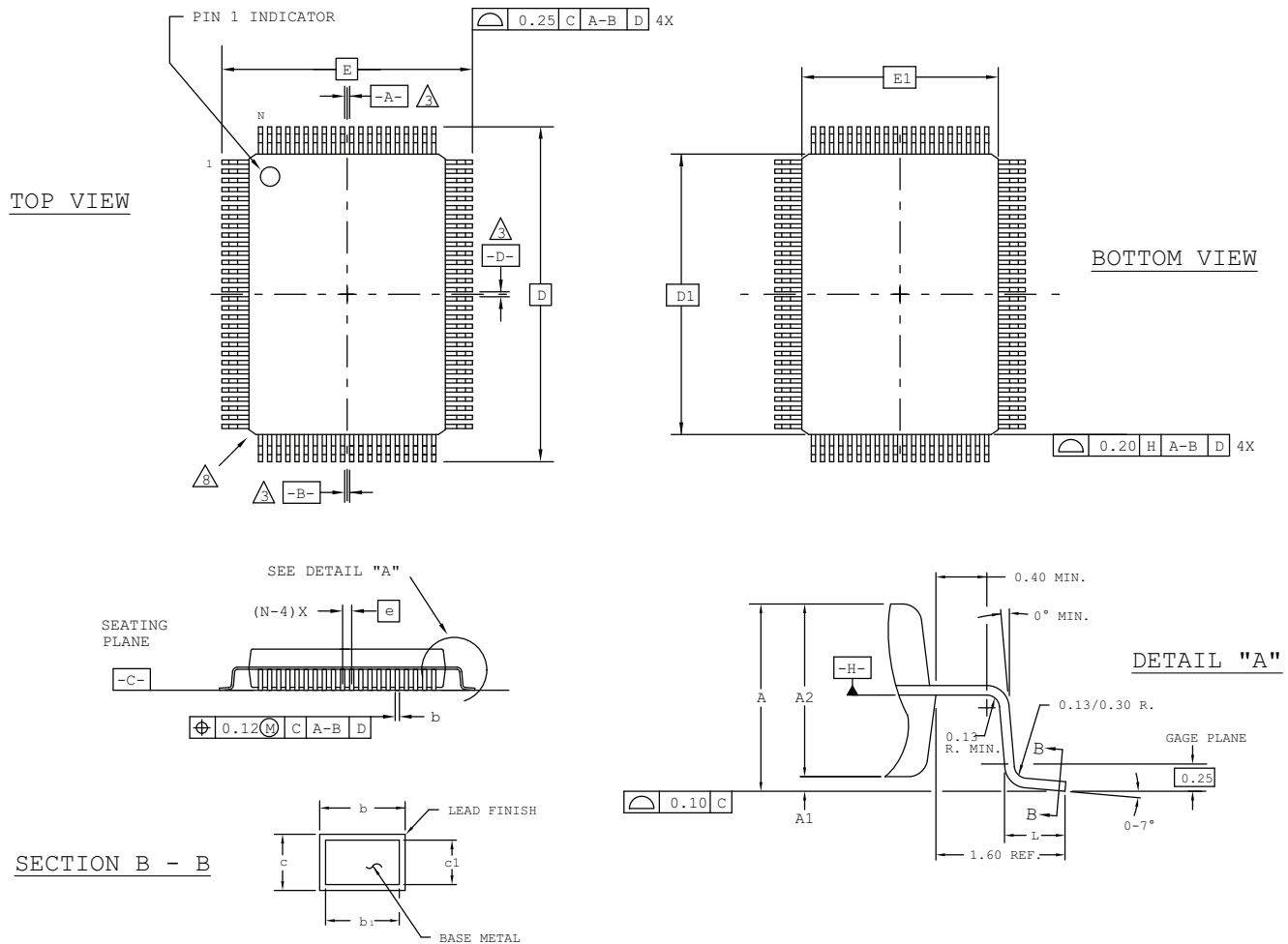


EXACT SHAPE AND SIZE OF THIS FEATURE IS OPTIONAL.

SYMBOL	MIN.	NOM.	MAX.
A	–	–	1.00
A1	0.11	–	–
A2	0.61	–	–
D/E	6.50 BSC		
M/N	5.85 BSC		
S	0.325 BSC		
b	0.20	0.25	0.30
e	0.65 BSC		
aaa	0.10		
bbb	0.10		
ccc	0.08		
ddd	0.15		
eee	0.05		

## 100-Pin PQFP Package

Dimensions in Millimeters



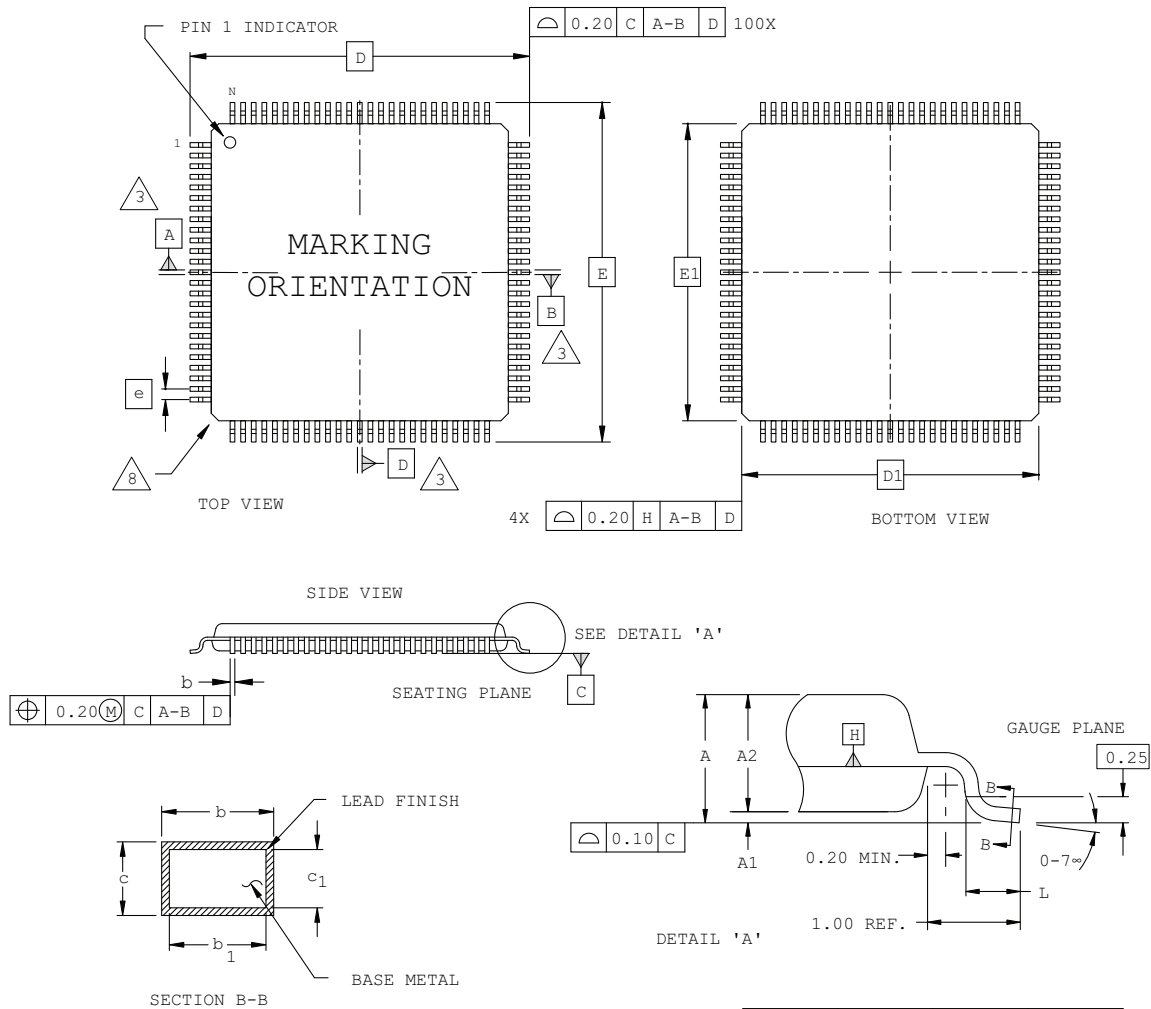
### NOTES:

- 1.0 DIMENSIONING AND TOLERANCING PER ANSI Y14.5 - 1982.
- 2.0 ALL DIMENSIONS ARE IN MILLIMETERS.
- 3.0 DATUMS A, B AND D TO BE DETERMINED AT DATUM PLANE H.
- 4.0 DIMENSIONS D1 AND E1 DO NOT INCLUDE MOLD PROTRUSION. ALLOWABLE MOLD PROTRUSION IS 0.254 MM ON D1 AND E1 DIMENSIONS.
- 5.0 THE TOP OF PACKAGE MAY BE SMALLER THAN THE BOTTOM OF THE PACKAGE BY 0.15 MM.
- 6.0 SECTION B-B:  
THESE DIMENSIONS APPLY TO THE FLAT SECTION OF THE LEAD BETWEEN 0.10 AND 0.25 MM FROM THE LEAD TIP.
- 7.0 A1 IS DEFINED AS THE DISTANCE FROM THE SEATING PLANE TO THE LOWEST POINT ON THE PACKAGE BODY.
- 8.0 EXACT SHAPE OF EACH CORNER IS OPTIONAL.
- 9.0 EXACT SHAPE OF EXPOSED HEATSINK IS OPTIONAL.

SYMBOL	MIN.	NOM.	MAX.
A	-	-	3.40
A1	0.25	-	0.50
A2	2.50	2.70	2.90
D	23.20 BSC		
D1	20.00 BSC		
E	17.20 BSC		
E1	14.00 BSC		
L	0.73	0.88	1.03
N	100		
e	0.65 BSC		
b	0.22	-	0.40
b1	0.22	0.30	0.36
c	0.11	-	0.23
c1	0.11	0.15	0.19

## 100-Pin TQFP Package Option 1: MachXO2, MachXO™, ispMACH® 4000

Dimensions in Millimeters



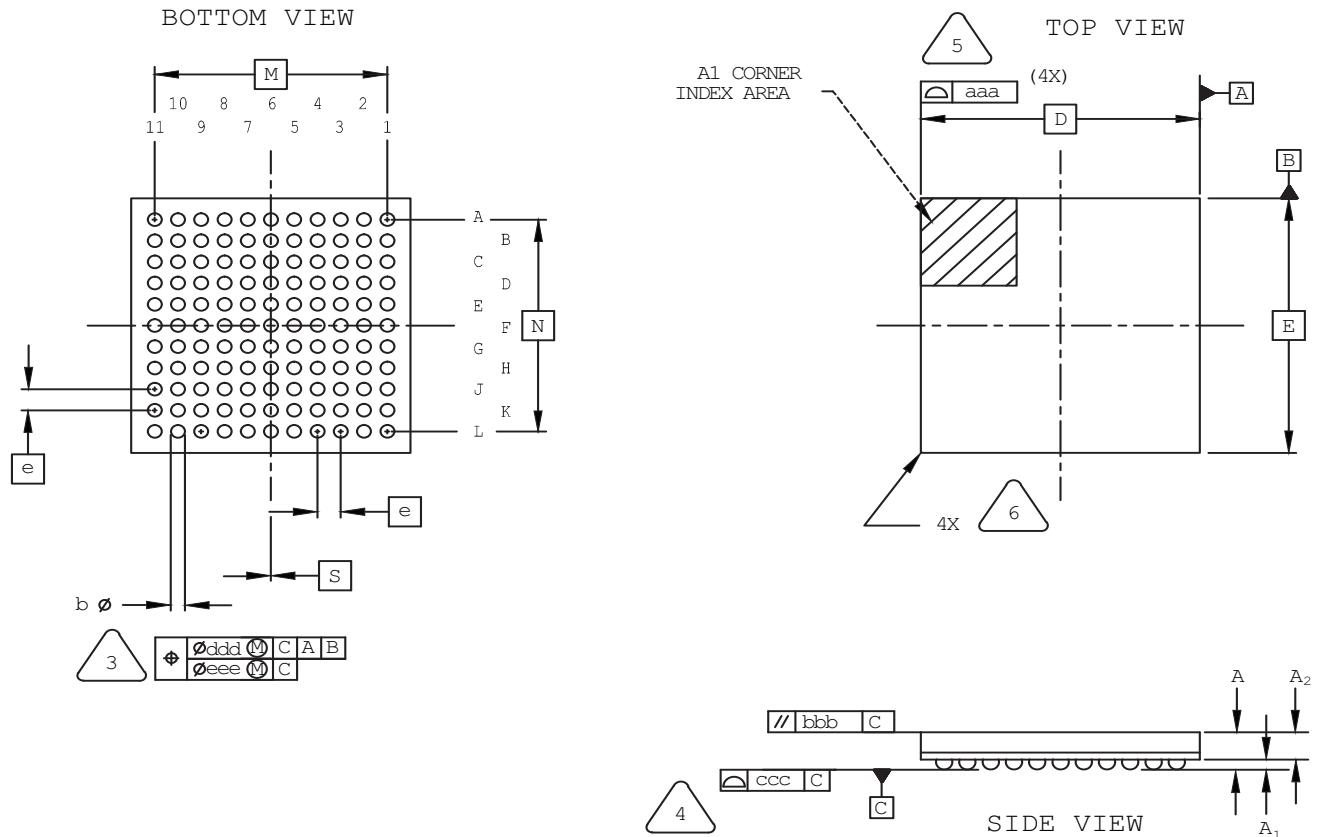
### NOTES:

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5 - 1982.
2. ALL DIMENSIONS ARE IN MILLIMETERS.
3. DATUMS A, B AND D TO BE DETERMINED AT DATUM PLANE H.
4. DIMENSIONS D1 AND E1 DO NOT INCLUDE MOLD PROTRUSION. ALLOWABLE MOLD PROTRUSION IS 0.254 MM ON D1 AND E1 DIMENSIONS.
5. THE TOP OF PACKAGE MAY BE SMALLER THAN THE BOTTOM OF THE PACKAGE BY 0.15 MM.
6. SECTION B-B:  
THESE DIMENSIONS APPLY TO THE FLAT SECTION OF THE LEAD BETWEEN 0.10 AND 0.25 MM FROM THE LEAD TIP.
7. A1 IS DEFINED AS THE DISTANCE FROM THE SEATING PLANE TO THE LOWEST POINT ON THE PACKAGE BODY.
8. EXACT SHAPE OF EACH CORNER IS OPTIONAL.

SYMBOL	MIN.	NOM.	MAX.
A	-	-	1.60
A1	0.05	-	0.15
A2	1.35	1.40	1.45
D	16.00 BSC		
D1	14.00 BSC		
E	16.00 BSC		
E1	14.00 BSC		
L	0.45	0.60	0.75
N	100		
e	0.50 BSC		
b	0.17	0.22	0.27
b1	0.17	0.20	0.23
c	0.09	0.15	0.20
c1	0.09	0.13	0.16

## 121-Ball csfBGA Package

Dimensions in Millimeters



NOTES: UNLESS OTHERWISE SPECIFIED

1. DIMENSIONS AND TOLERANCES PER ANSI Y14.5M.

2. ALL DIMENSIONS ARE IN MILLIMETERS.

3. DIMENSION "b" IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM [C].

4. PRIMARY DATUM [C] AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.

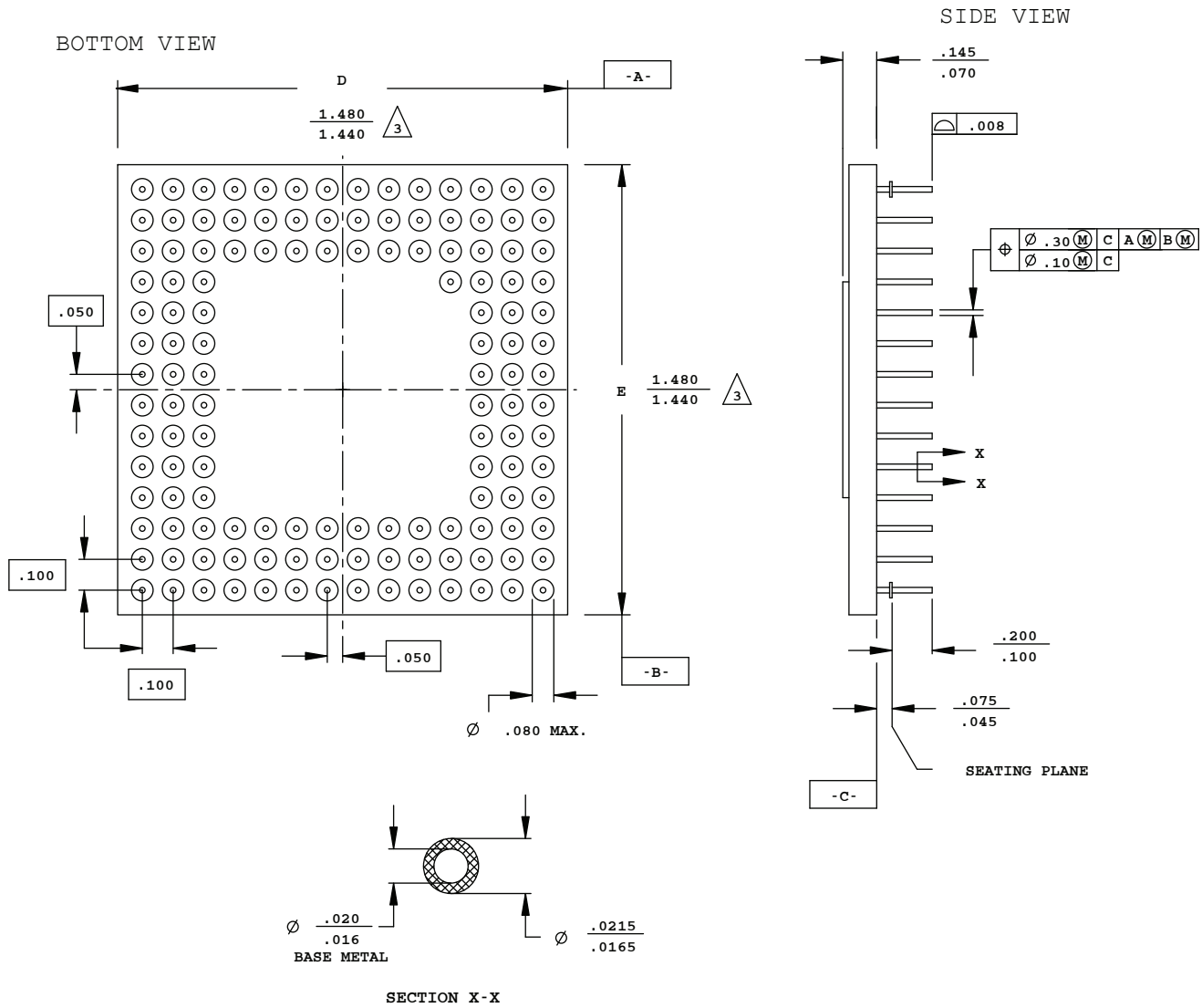
5. BILATERAL TOLERANCE ZONE IS APPLIED TO EACH SIDE OF THE PACKAGE BODY.

6. EXACT SHAPE AND SIZE OF THIS FEATURE IS OPTIONAL.

SYMBOL	MIN.	NOM.	MAX.
A	—	—	1.00
A1	0.15	0.24	—
A2	—	0.66	—
D/E	6.00 BSC		
M/N	5.00 BSC		
S	0.00 BSC		
b	0.25	0.30	0.35
e	0.50 BSC		
aaa	0.10		
bbb	0.10		
ccc	0.08		
ddd	0.15		
eee	0.05		

# 133-Pin CPGA Package

Dimensions in Inches



## NOTES:

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M.
2. ALL DIMENSIONS ARE IN INCHES.

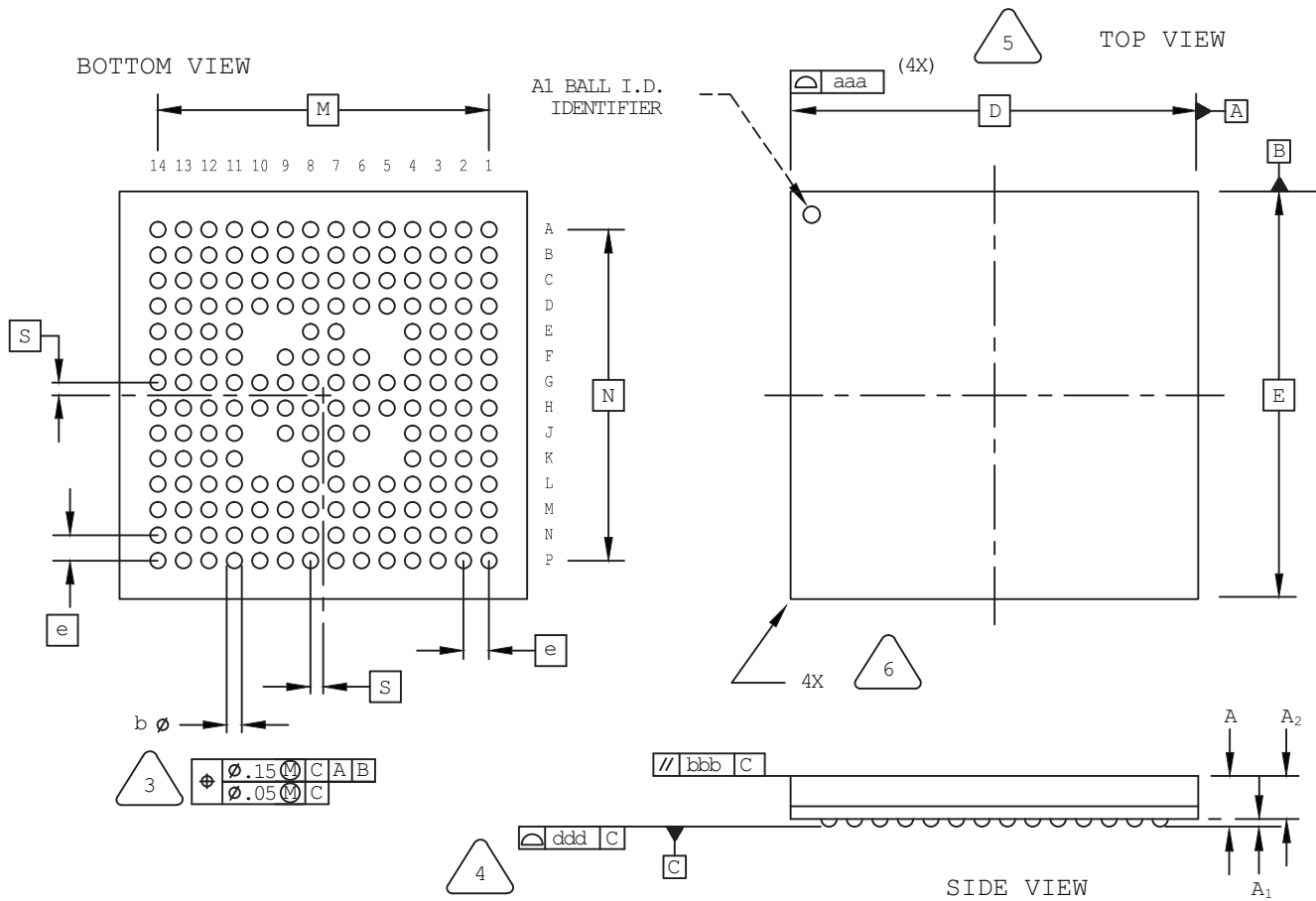


DIMENSIONS D AND E MAY HAVE MATERIAL PROTRUSION OF .006 INCHES MAXIMUM ABOVE THE DIMENSION SHOWN NOT TO EXCEED .003 INCHES MAXIMUM PER SIDE.



# 184-Ball csBGA Package

Dimensions in Millimeters



NOTES: UNLESS OTHERWISE SPECIFIED

- DIMENSIONS AND TOLERANCES PER ANSI Y14.5M.
- ALL DIMENSIONS ARE IN MILLIMETERS.



DIMENSION "b" IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM C



PRIMARY DATUM C AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.



BILATERAL TOLERANCE ZONE IS APPLIED TO EACH SIDE OF THE PACKAGE BODY.

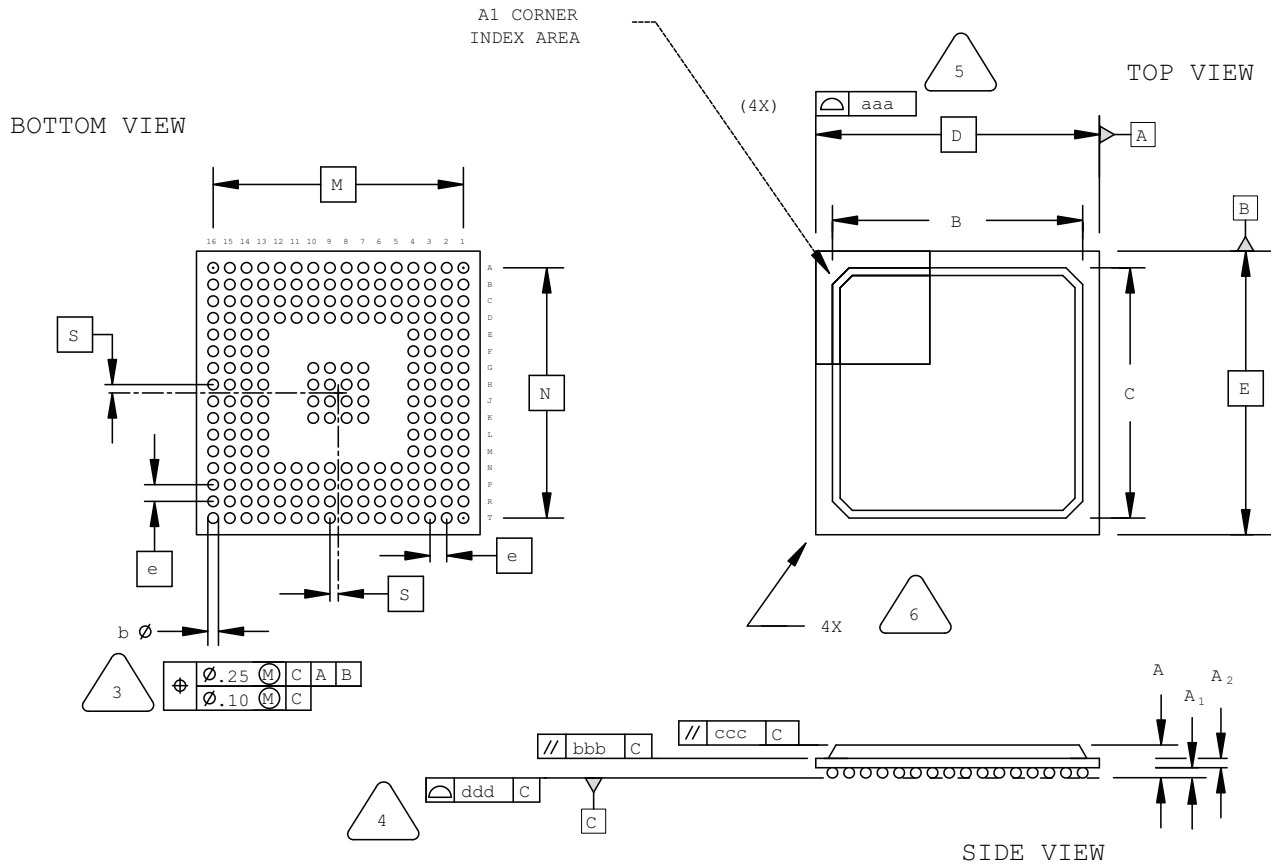


EXACT SHAPE AND SIZE OF THIS FEATURE IS OPTIONAL.

SYMBOL	MIN.	NOM.	MAX.
A	1.20	1.35	1.50
A1	0.16	-	-
A2	-	-	1.34
D/E	8.00 BSC		
M/N	6.50 BSC		
S	0.25 BSC		
b	0.25	0.30	0.35
e	0.50 BSC		
aaa	-	-	0.10
bbb	-	-	0.10
ddd	-	-	0.08

## 208-Ball fpBGA Package

Dimensions in Millimeters



NOTES: UNLESS OTHERWISE SPECIFIED

- DIMENSIONS AND TOLERANCES PER ANSI Y14.5M.
- ALL DIMENSIONS ARE IN MILLIMETERS.



DIMENSION "b" IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM  $\boxed{C}$



PRIMARY DATUM  $\boxed{C}$  AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.



BILATERAL TOLERANCE ZONE IS APPLIED TO EACH SIDE OF THE PACKAGE BODY.

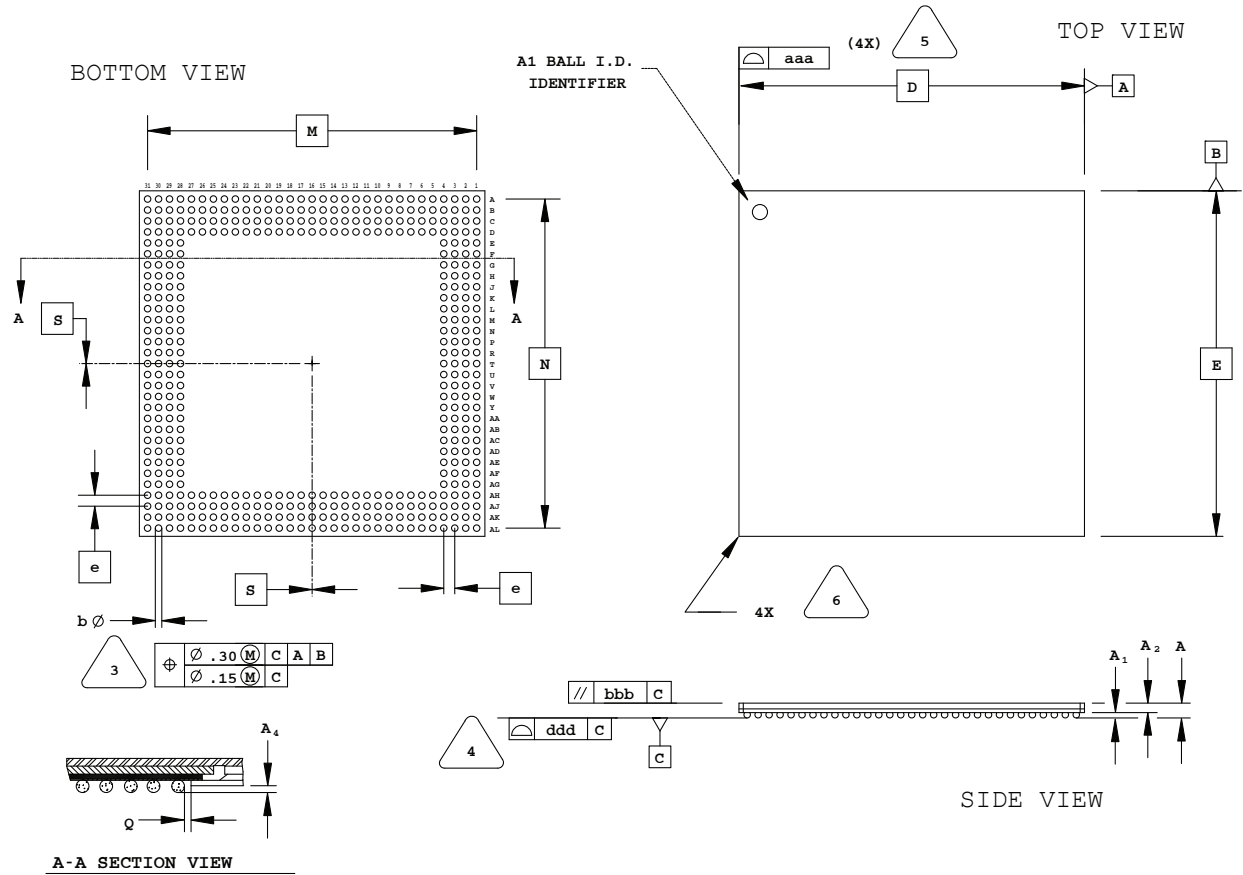


EXACT SHAPE AND SIZE OF THIS FEATURE IS OPTIONAL.

SYMBOL	MIN.	NOM.	MAX.
A	1.30	1.70	2.10
A1	0.30	0.50	0.70
A2	0.30	0.50	0.70
B/C	14.80	15.30	15.80
D/E	17.00 BSC		
M/N	15.00 BSC		
S	0.50 BSC		
b	0.50	0.60	0.70
e	1.00 BSC		
aaa	-	-	0.20
bbb	-	-	0.25
ccc	-	-	0.35
ddd	-	-	0.20

## 432-Ball SBGA Package

Dimensions in Millimeters



NOTES: UNLESS OTHERWISE SPECIFIED

1. DIMENSIONS AND TOLERANCES PER ANSI Y14.5M.
2. ALL DIMENSIONS ARE IN MILLIMETERS.



DIMENSION "b" IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM **C**



PRIMARY DATUM **C** AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.



BILATERAL TOLERANCE ZONE IS APPLIED TO EACH SIDE OF THE PACKAGE BODY.

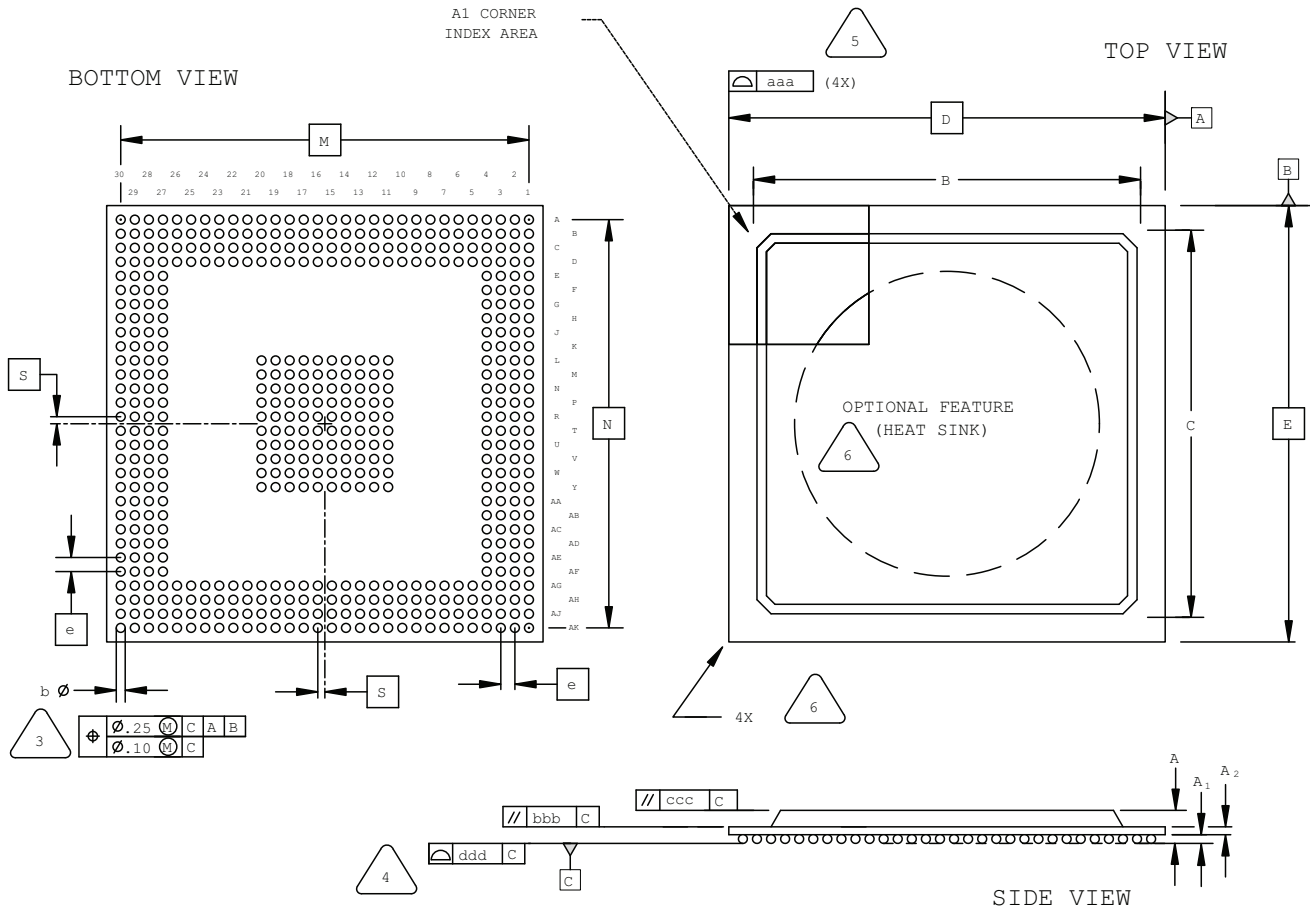


EXACT SHAPE AND SIZE OF THIS FEATURE IS OPTIONAL.

SYMBOL	MIN.	NOM.	MAX.
A	-	-	1.70
A1	0.50	0.65	0.80
A2	0.80	0.90	1.00
D/E	40.00 BSC		
M/N	38.10 BSC		
S	0.00 BSC		
b	0.60	0.75	0.90
e	1.27 BSC		
Q	0.25	-	-
A4	0.10	-	-
aaa	-	-	0.20
bbb	-	-	0.25
ddd	-	-	0.20

# 516-Ball fpBGA Package

Dimensions in Millimeters



NOTES: UNLESS OTHERWISE SPECIFIED

- DIMENSIONS AND TOLERANCES PER ANSI Y14.5M.
- ALL DIMENSIONS ARE IN MILLIMETERS.



DIMENSION "b" IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM C



PRIMARY DATUM C AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.



BILATERAL TOLERANCE ZONE IS APPLIED TO EACH SIDE OF THE PACKAGE BODY.

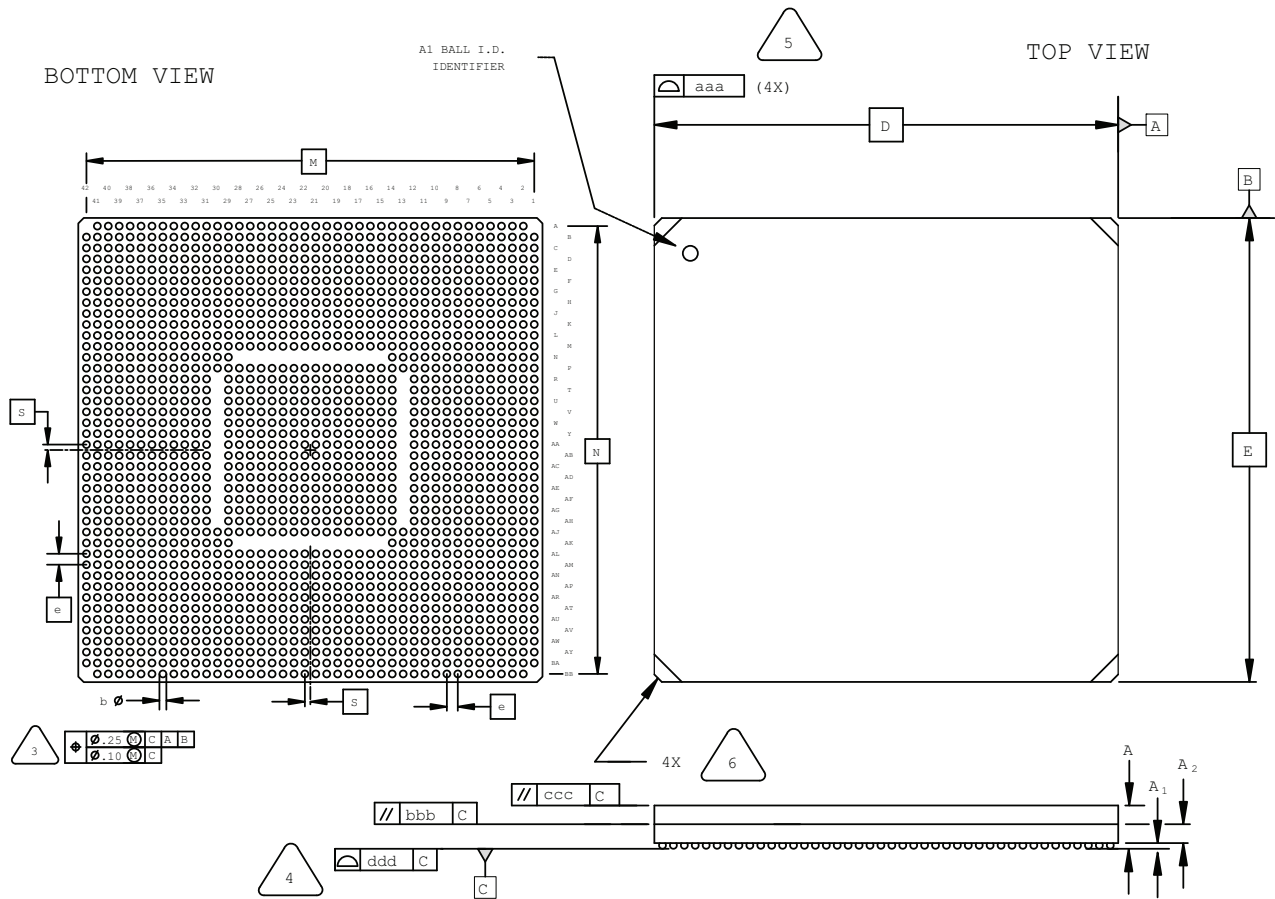


EXACT SHAPE AND SIZE OF THIS FEATURE IS OPTIONAL.

SYMBOL	MIN.	NOM.	MAX.
A	1.70	2.15	2.60
A1	0.30	0.50	0.70
A2	0.30	0.50	0.70
B/C	25.80	27.55	29.30
D/E	31.00 BSC		
M/N	29.00 BSC		
S	0.50 BSC		
b	0.50	0.60	0.70
e	1.00 BSC		
aaa	-	-	0.20
bbb	-	-	0.25
ccc	-	-	0.35
ddd	-	-	0.20

# 1704-Ball Ceramic fcBGA Package

Dimensions in Millimeters



NOTES: UNLESS OTHERWISE SPECIFIED

1. DIMENSIONS AND TOLERANCES PER ANSI Y14.5M.
2. ALL DIMENSIONS ARE IN MILLIMETERS.



DIMENSION "b" IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM **C**.

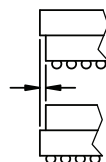


PRIMARY DATUM **C** AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.



BILATERAL TOLERANCE ZONE IS APPLIED TO EACH SIDE OF THE PACKAGE BODY. PACKAGE BODY INCLUDES SUBSTRATE AND LID.

MAXIMUM OFFSET: 0.20 mm



EXACT SHAPE AND SIZE OF THIS FEATURE IS OPTIONAL.

SYMBOL	MIN.	NOM.	MAX.
A	4.30	4.80	5.30
A1	0.30	0.50	0.70
A2	1.30	1.60	1.90
D/E	42.50 BSC		
M/N	41.00 BSC		
S	0.50 BSC		
b	0.50	0.60	0.70
e	1.00 BSC		
aaa	-	-	0.20
bbb	-	-	0.25
ccc	-	-	0.35
ddd	-	-	0.20